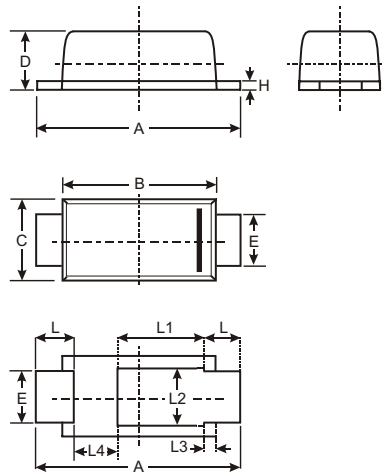


Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- High Surge Capability
- High Current Capability and Low Forward Voltage Drop
- Lead Free Finish, RoHS Compliant (Note 5)**
- "Green" Molding Compound (No Br, Sb)**

Mechanical Data

- Case: PowerDI™ 123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Marking & Type Code Information: See Last Page
- Weight: 0.01 grams (approx.)
- Ordering Information: See Last Page



PowerDI™123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.45	0.85	0.65
L1	—	—	1.35
L2	—	—	1.10
L3	—	—	0.20
L4	0.90	1.30	1.05
All Dimensions in mm			

Maximum Ratings @ T_A = 25°C unless otherwise specified

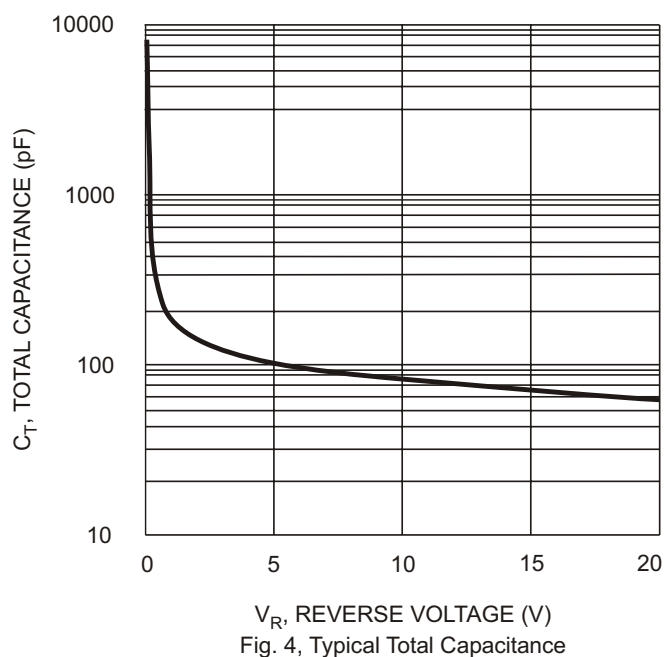
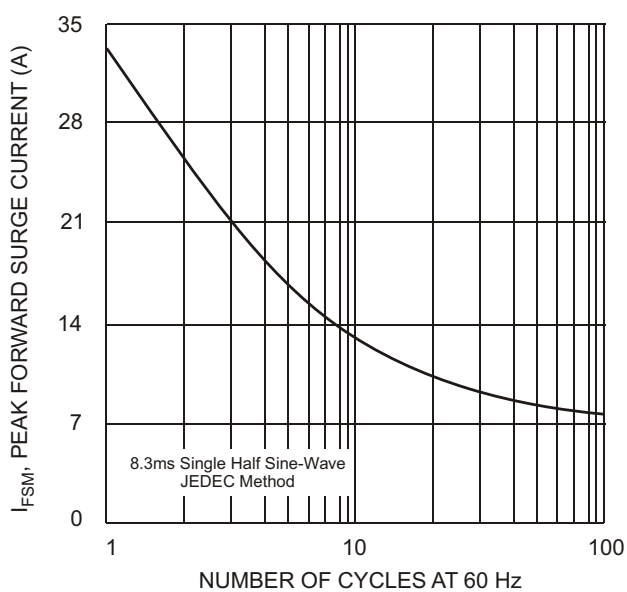
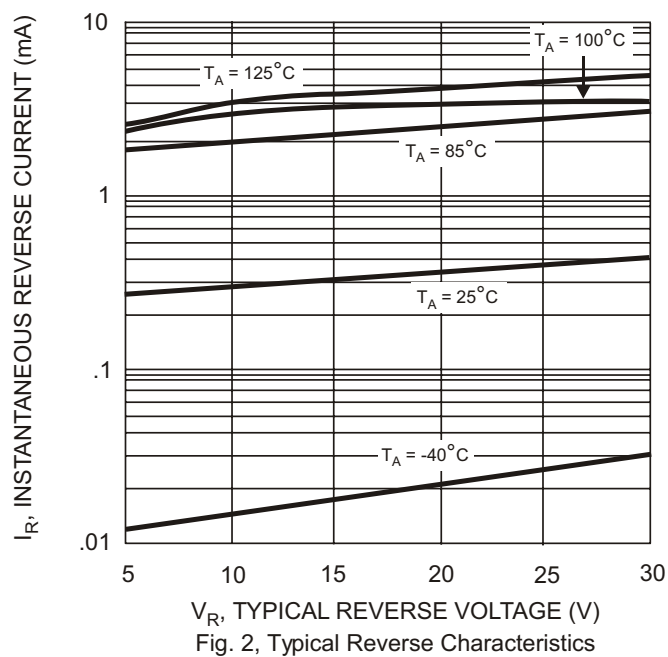
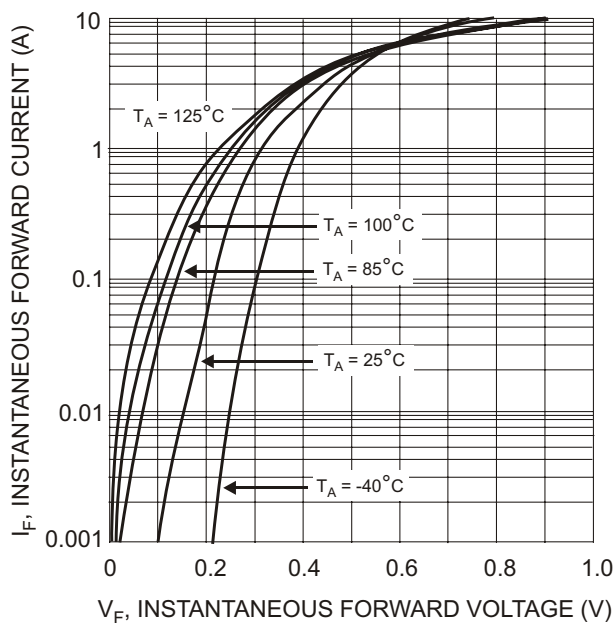
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	30	V
RMS Reverse Voltage	$V_R(RMS)$	21	V
Average Forward Current @ T _T = 121°C	$I_F(AV)$	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	33	A
Power Dissipation (Note 1)	P_D	1.67	W
Power Dissipation (Note 2)	P_D	556	mW
Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	60	°C/W
Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	180	°C/W
Thermal Resistance Junction to Soldering (Note 3)	$R_{\theta JS}$	10	°C/W
Operating Temperature Range	T_j	-40 to +125	°C
Storage Temperature Range	T_{STG}	-40 to +150	°C

Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	$V_{(BR)R}$	30	—	—	V	$I_R = 1.0mA$
Forward Voltage (Note 4)	V_F	—	0.310 0.375	— 0.420	V	$I_F = 1.0A$ $I_F = 2.0A$
Leakage Current (Note 4)	I_R	—	0.260 —	— 1.0	mA	$V_R = 5V, T_A = 25°C$ $V_R = 30V, T_A = 25°C$
Total Capacitance	C_T	—	76	—	pF	$V_R = 10V, f = 1.0MHz$

- Notes:
- Part mounted on 2"x2" GETEK board with 1"x1" copper pad, 25% anode, 75% cathode.
 - Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 - Theoretical $R_{\theta JS}$ calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 - Short duration pulse test to minimize self-heating effect.
 - RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.

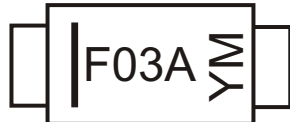


Ordering Information (Note 6)

Device	Packaging	Shipping
DFLS230L-7	PowerDI™ 123	3000/Tape & Reel

Notes: 6. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



F03A = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: R = 2004)
M = Month (ex: 9 = September)

Date Code Key

Year	2004	2005	2006	2007	2008	2009
Code	R	S	T	U	V	W

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D